

DOCKET NO: 312302US40PCT



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
HUI ZHONG, ET AL. : EXAMINER: TUAN T. DINH
SERIAL NO: 10/049,270 :
FILED: JUNE 27, 2002 : GROUP ART UNIT: 2841
FOR: MULTILAYER PRINTED WIRING :
BOARD, SOLDER RESIST
COMPOSITION, METHOD FOR
MANUFACTURING MULTILAYER
PRINTED WIRING BOARD, AND
SEMICONDUCTOR DEVICE

AMENDMENT

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated November 5, 2007, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this paper.

Amendments to the Drawings begin on page 6 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 7 of this paper.